

Information note

N° 044/21

Dear customer,

With this Infineon Technologies AG information note, we would like to inform you about the following

Second source substrate supplier and change of the pre-plating of the PrimePACK™ IGBT5/.XT substrates



On 16 April 2020, Infineon acquired Cypress.

We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance.

For further details, please visit our website:

https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/

Infineon Technologies AG

Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0

Chairman of the Supervisory Board: Dr. Wolfgang Eder

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492



Information note

N° 044/21

Products affected

Please refer to affected product list 1_cip04421

▶ Detailed change information

Subject •

- Second source substrate supplier
- Harmonization of the PrimePACK[™] substrates

Reason •

- Ensure security of supply by release of second source substrate supplier for PrimePACK™ .XT
- Module production process harmonization of PrimePACK™ substrates

Desc	rin	tio	n
Desc	ıιμ	uo	••

on	<u>Old</u>	New	
	Single source substrate supplier	Second sourcing of substrate supplier	
	 Partial pre-plating on the substrate at the chip positions 	None pre-plating on the substrate	

- Product identification
- Date code
- ► Impact of change
- Beside the above-mentioned changes, the other specifications of the mentioned modules, like electrical- and mechanical module parameters, remain unchanged according to JEDEC Standard JESD46-C: form, fit, function and reliability.
- Attachments
- 1_cip04421.pdf affected product list
- Intended start of delivery

2021-09-01

If you have any questions, please do not hesitate to contact your local sales office.



Information note N° 044/21

Second source substrate supplier and change of the pre-plating of the PrimePACK IGBT5/.XT substrates

SP number	OPN	Package
SP000976764	FF1200R12IE5BPSA1	AG-PRIME2
SP001657864	FF1200R12IE5PBPSA1	AG-PRIME2
SP001426000	FF1200R17IP5BPSA1	AG-PRIME2
SP001663854	FF1200R17IP5PBPSA1	AG-PRIME2
SP001630414	FF1500R12IE5BPSA1	AG-PRIME3+
SP002397954	FF1500R12IE5PBPSA1	AG-PRIME3+
SP001630390	FF1500R17IP5BPSA1	AG-PRIME3+
SP002813348	FF1500R17IP5PBPSA1	AG-PRIME3+
SP001700760	FF1500R17IP5RBPSA1	AG-PRIME3
SP001495678	FF1800R12IE5BPSA1	AG-PRIME3+
SP001662006	FF1800R12IE5PBPSA1	AG-PRIME3+
SP001310752	FF1800R17IP5BPSA1	AG-PRIME3+
SP001635768	FF1800R17IP5PBPSA1	AG-PRIME3+
	SP000976764 SP001657864 SP001426000 SP001663854 SP001630414 SP002397954 SP001630390 SP002813348 SP001700760 SP001495678 SP001662006 SP001310752	SP000976764 FF1200R12IE5BPSA1 SP001657864 FF1200R12IE5PBPSA1 SP001426000 FF1200R17IP5BPSA1 SP001663854 FF1200R17IP5PBPSA1 SP001630414 FF1500R12IE5BPSA1 SP002397954 FF1500R12IE5PBPSA1 SP001630390 FF1500R17IP5BPSA1 SP002813348 FF1500R17IP5PBPSA1 SP001700760 FF1500R17IP5RBPSA1 SP001495678 FF1800R12IE5BPSA1 SP001662006 FF1800R12IE5PBPSA1 SP001310752 FF1800R17IP5BPSA1